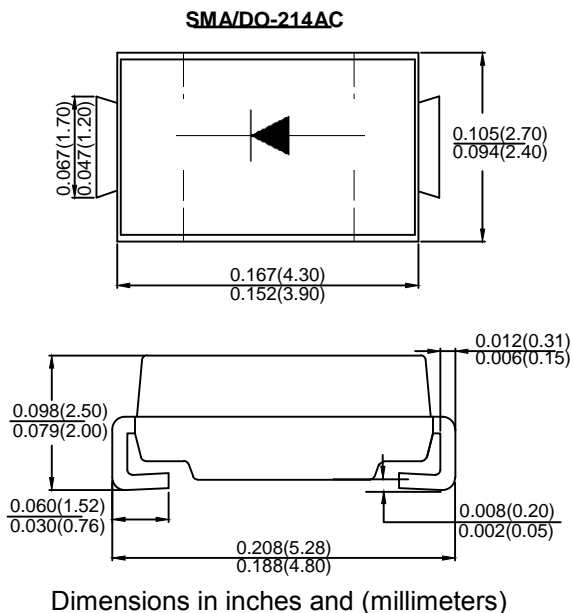


Features

- Schottky Brier Chip
- Low Power Loss,High Efficiency
- Ideally Suited for Automatic Assembly
- Surge Overload Rating to 30A Peak
- Plastic Case Material has UL Flammability Classification Rating 94V-0

Mechanical Data

- Case: Molded plastic SMA
- Terminals: Plated leads solderable per MIL-STD-750,Method 2026 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Making: Type Number



Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load

For capacitive load derate current by 20%

Type Number	SYMBOL	SS12	SS13	SS14	SS145	SS15	SS16	SS18	SS110	SS115	SS120	SS125	Unit	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	20	30	40	45	50	60	80	100	150	200	250	V	
Maximum RMS Voltage	V_{RMS}	14	21	28	31	35	42	56	70	105	140	175	V	
Maximum DC Blocking Voltage	V_{DC}	20	30	40	45	50	60	80	100	150	200	250	V	
Average Rectified Output Current @ $T_L = 100^\circ C$	$I_{F(AV)}$	1.0											A	
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30											A	
Rating for fusing ($t < 8.3ms$)	$I^2 t$	3.74											$A^2 s$	
Forward Voltage @ $I_F = 1.0A$ (Note 1)	V_{FM}	0.55			0.7		0.85		0.92		0.95		V	
Peak Reverse Current @ $T_A = 25^\circ C$	I_R	0.1						0.05						mA
At Rated DC Blocking Voltage @ $T_A = 100^\circ C$		10						5						
Typical Junction Capacitance	C_J	28											pF	
Typical Thermal Resistance per leg (Note 2)	$R_{\theta JL}$	88											$^\circ C/W$	
Operating Temperature Range	T_J	-55 to +150											$^\circ C$	
Storage Temperature Range	T_{STG}	-55 to +150											$^\circ C$	

Note: 1. Pulse Test with PW=300usec, 1% Duty Cycle.

2. Mounted on P.C. Board with 5.0 mm² (0.13mm thick) copper pad areas.

Fig. 1 Forward Current Derating Curve

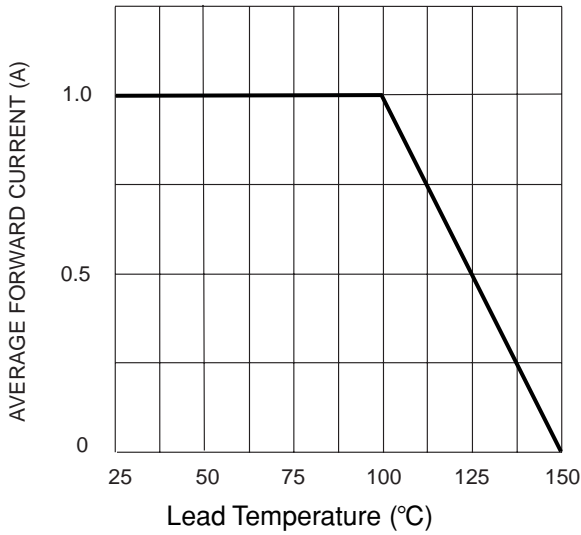


Fig. 2 Typ. Forward Characteristics

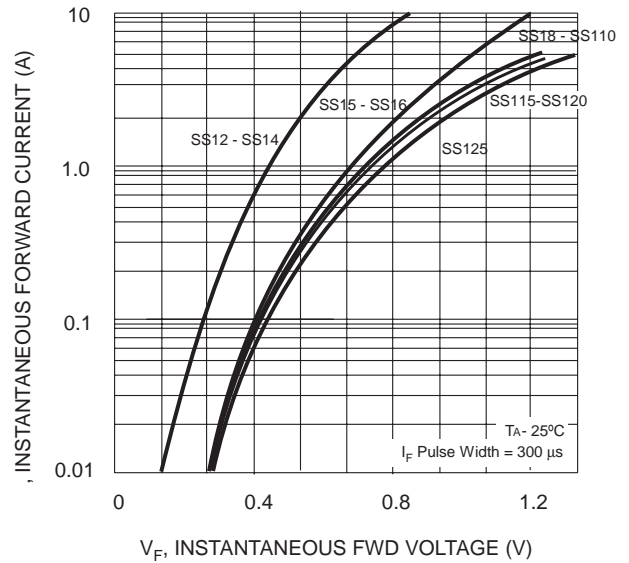


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

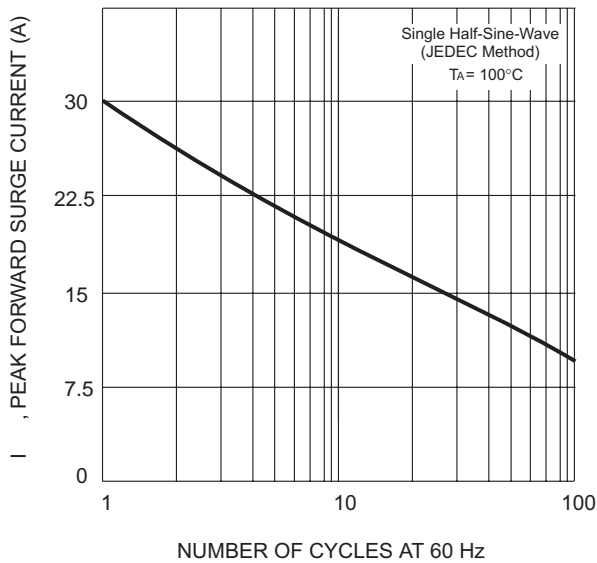
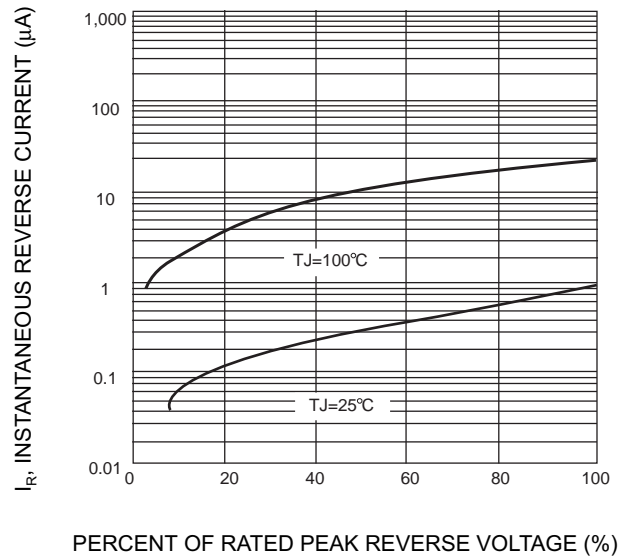
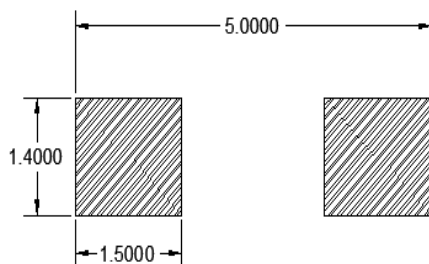


Fig. 4 T typical Reverse Characteristics (per element)



SMA PAD LAYOUT



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